

REMARKS

Claims 1, 2 and 4 through 7 remain pending in this application. In response to the final Office Action dated November 15, 2005, claim 1 has been amended. A Request for Continued Examination Transmittal is filed herewith. Care has been taken to avoid the addition of new matter. Allowance of the application is respectfully solicited.

Claim 1 stands rejected under 35 U.S.C. § 102(e) as being anticipated U.S. published patent application 2002/192928 (Kosugi). Claim 2 stands under objection solely for its dependency from rejected parent claim 1. In response, claim 1 has been amended.

Claim 1 now requires that the monitoring pad include at least two exposed surfaces separated by space from each other, the two surfaces electrically connected to each other via an inner metal wiring layer to form a single monitoring pad. One of the exposed surfaces is located in an area to be cut away by a dicing blade, another of the exposed surfaces located outside the cut away area, the space between the two surfaces containing a cutting line for the dicing blade. The amendment is supported by the original disclosure, for example, as shown in Fig. 3 and its accompanying description in the specification. It is submitted that Kosugi neither discloses nor suggests such claimed arrangement.

As the cutting area between wafer chip areas for a dicing blade has become narrower, it has become difficult to arrange monitoring pads having enough size for proper contact with a test probe inside the narrow cutting area. In the claimed invention, the exposed surface arranged inside the cutting area and the exposed surface arranged outside the cutting area are electrically connected via inner layered wiring. The connected exposed surfaces act as one monitoring pad. The test probe can connect to the test circuit by contacting any one of the exposed surfaces.

Kosugi discloses a resistor circuit 18a having a pair of probe pads 20 and a resistance wire 22 electrically connecting between the paired probe pads 20 (paragraph [0027]). The

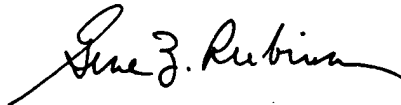
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manufacturing precision of the regions adjacent to the resistor circuit can be evaluated from the amount of resistance of the resistance wire (paragraph [0004]). In Kosugi, each of the paired probe pads 20 is an electrically individual electrode when measuring the amount of resistance. The paired probe pads cannot act as one monitoring pad. Each of two test probes must be connected to a respective probe pad of the paired probe pads to measure the resistance. As Kosugi does not disclose one monitoring pad having plural exposed surfaces, claim 1 is patentably distinguishable.

Accordingly, allowance of the application is respectfully solicited. To the extent necessary, a petition for an extension of time under 37 C.F.R. 1.136 is hereby made. Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account 500417 and please credit any excess fees to such deposit account.

Respectfully submitted,

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